



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/ContentPage.aspx?pageid=M aterials-Declaration

Form Type*
Distribute
Class 6 -

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg
Infomation

Supplier Information			
Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sep 26, 2014 03:09 AM
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Num	ber Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type	
RB751S40	RB751S40	SOD523F-2 (G).csv			TAKCHEONG	0.002398	g	Each	
							_		
Manufacturing P	rocess Information								
Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Boo	ly Temperature	Max Time at Peak Temperature		No Re	No Reflow cycles	
Sn	Copper Alloy	1	260 C		30 seconds		3		

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

none

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

David Loneasto

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOD523F-2 (G).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.031	Supplier		Silicon	0.031	7440-21-3	12926
Encapsulation	Thermoplastics	0.92	Supplier		Carbon Black	0.009	1333-86-4	3836
			Supplier		Epoxy Resin	0.184	29690-82-2	76724
			Supplier		Silica, vitreous	0.727	60676-86-0	303059
Lead Frame	Copper & its alloys	0.722	Supplier		Copper	0.636	7440-50-8	265197
			Supplier		Iron	0.017	7439-89-6	7225
			Supplier		Phosphorus	0.001	7723-14-0	271
			Supplier		Tin	0.067	7440-31-5	27979
			Supplier		Zinc	0.001	7440-66-6	391
Plating	Other Nonferrous metals & alloys	0.722	Supplier		Tin	0.722	7440-31-5	301057
Wire Bond	Precious metals	0.003	Supplier		Gold	0.003	7440-57-5	1334